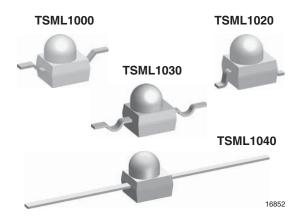


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# High Power Infrared Emitting Diode, RoHS Compliant, 940 nm, GaAlAs/GaAs



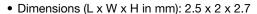
#### DESCRIPTION

TSML1000 is an infrared, 940 nm emitting diode in GaAlAs/GaAs with high radiant power molded in a clear, untinted plastic package (with lens) for surface mounting (SMD).

### **FEATURES**

Package type: surface mount





Peak wavelength: λ<sub>p</sub> = 940 nm

High radiant power

· High radiant intensity

• Angle of half intensity:  $\varphi = \pm 12^{\circ}$ 

Low forward voltage

· Suitable for high pulse current operation

· Good spectral matching with Si photodetectors

· Versatile terminal configurations

Package matches with detector TEMT1000

• Floor life: 168 h, MSL 3, acc. J-STD-020

• Compliant to RoHS Directive 2002/95/EC and in accordance with WEEE 2002/96/EC

#### APPLICATIONS

- · For remote control
- Punched tape readers
- Encoder
- Photointerrupters

PRODUCT SUMMARY				
COMPONENT	I <sub>e</sub> (mW/sr)	φ (deg)	λ <sub>P</sub> (nm)	t <sub>r</sub> (ns)
TSML1000	7	± 12	940	800
TSML1020	7	± 12	940	800
TSML1030	7	± 12	940	800
TSML1040	7	± 12	940	800

Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
TSML1000	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing		
TSML1020	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing		
TSML1030	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Yoke		
TSML1040	Bulk	MOQ: 1000 pcs, 1000 pcs/bulk	Axial leads		

· MOQ: minimum order quantity

Thermal resistance junction/ambient

# TSML1000, TSML1020, TSML1030, TSML1040

 $R_{thJA} \\$ 

120

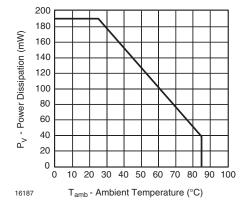
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°C

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT	
Reverse voltage		V <sub>R</sub>	5	V	
Forward current		I <sub>F</sub>	100	mA	
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu s$	I <sub>FM</sub>	200	mA	
Surge forward current	t <sub>p</sub> = 100 μs	I <sub>FSM</sub>	1.0	Α	
Power dissipation		P <sub>V</sub>	190	mW	
Junction temperature		Tj	100	°C	
Operating temperature range		T <sub>amb</sub>	- 40 to + 85	°C	
Storage temperature range		T <sub>stg</sub>	- 40 to + 100	°C	
Soldering temperature	t ≤ 5 s	T <sub>sd</sub>	< 260	°C	

Soldered on PCB, pad dimensions:

4 mm x 4 mm



100 (VE) 100 80 40 40 20 0 10 20 30 40 50 60 70 80 90 100 16188 T<sub>amb</sub> - Ambient Temperature (°C)

400

Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

Fig. 2 - Forward Current vs. Ambient Temperature

<b>BASIC CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Famound online	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	V <sub>F</sub>		1.2	1.5	V
Forward voltage	$I_F = 1 \text{ A}, t_p = 100 \mu \text{s}$	V <sub>F</sub>		2.6		V
Temperature coefficient of V <sub>F</sub>	I <sub>F</sub> = 1 mA	TK <sub>VF</sub>		- 1.8		mV/K
Reverse current	V <sub>R</sub> = 5 V	I <sub>R</sub>			10	μΑ
Junction capacitance	V <sub>R</sub> = 0 V, f = 1 MHz, E = 0	Cj		25		pF
Radiant intensity	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	l <sub>e</sub>	3	7	15	mW/sr
Radiant power	$I_F = 100 \text{ mA}, t_p = 20 \text{ ms}$	φ <sub>e</sub>		35		mW
Temperature coefficient of φ <sub>e</sub>	I <sub>F</sub> = 20 mA	TKφ <sub>e</sub>		- 0.6		%/K
Angle of half intensity		φ		± 12		deg
Peak wavelength	I <sub>F</sub> = 100 mA	$\lambda_{p}$		940		nm
Spectral bandwidth	I <sub>F</sub> = 100 mA	Δλ		50		nm
Temperature coefficient of $\lambda_p$	I <sub>F</sub> = 100 mA	TKλ <sub>p</sub>		0.2		nm/K
Rise time	I <sub>F</sub> = 100 mA	t <sub>r</sub>		800		ns
Fall time	I <sub>F</sub> = 100 mA	t <sub>f</sub>		800		ns
Virtual source diameter		d		1.2		mm

### **BASIC CHARACTERISTICS** (T<sub>amb</sub> = 25 °C, unless otherwise specified)

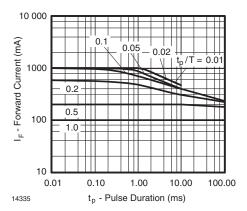


Fig. 3 - Pulse Forward Current vs. Pulse Duration

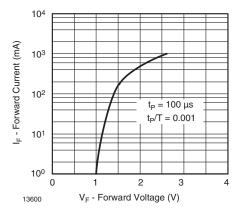


Fig. 4 - Forward Current vs. Forward Voltage

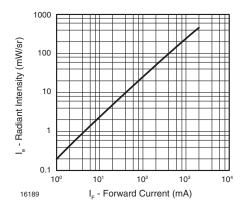


Fig. 5 - Radiant Intensity vs. Forward Current

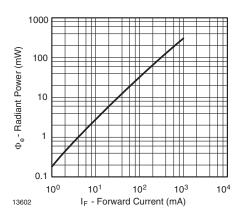


Fig. 6 - Radiant Power vs. Forward Current

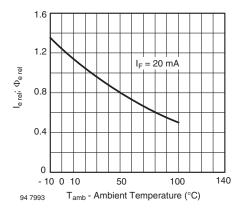


Fig. 7 - Relative Radiant Intensity/Power vs. Ambient Temperature

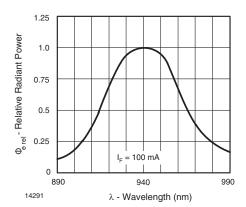


Fig. 8 - Relative Radiant Power vs. Wavelength

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### **REFLOW SOLDER PROFILE**

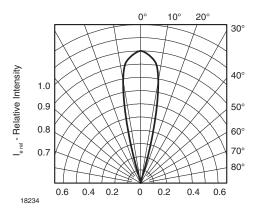


Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

#### PRECAUTIONS FOR USE

#### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (burn out will happen).

#### 2. Storage

- 2.1 Storage temperature and rel. humidity conditions are: 5 °C to 35 °C, R.H. 60 %.
- 2.2 Floor life must not exceed 168 h, acc. to JEDEC level 3, J-STD-020.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with desiccant.

Considering tape life, we suggest to use products within one year from production date.

- 2.3 If opened more than one week in an atmosphere 5 °C to 35 °C, R.H. 60 %, devices should be treated at 60 °C ± 5 °C for 15 h.
- 2.4 If humidity indicator in the package shows pink color (normal blue), then devices should be treated with the same conditions as 2.3.

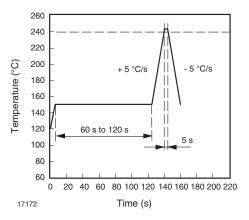
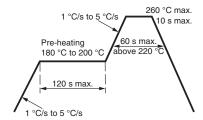


Fig. 10 - Lead Tin (SnPb) Reflow Solder Profile

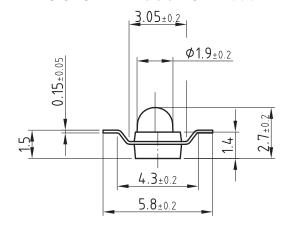


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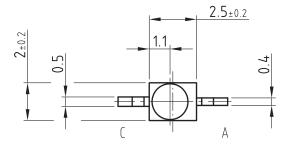
Fig. 11 - Lead (Pb)-Free Reflow Solder Profile acc. J-STD-020

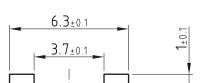


### **PACKAGE DIMENSIONS** in millimeters: TSML1000









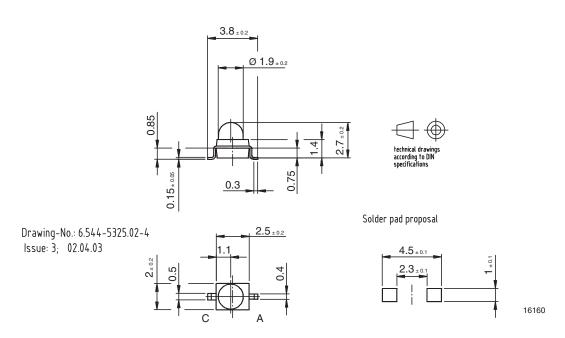
Solder pad proposal

Drawing-No.: 6.544-5326.02-4

Issue: 3: 02.04.03

16159

### **PACKAGE DIMENSIONS** in millimeters: TSML1020

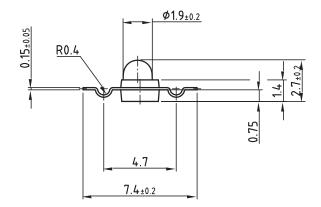




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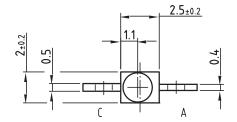
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### **PACKAGE DIMENSIONS** in millimeters: TSML1030

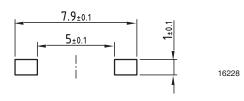


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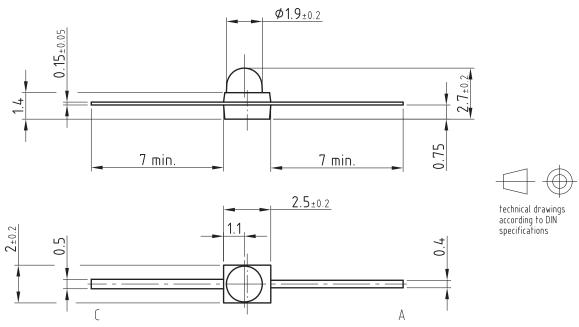




Solder pad proposal



### PACKAGE DIMENSIONS in millimeters: TSML1040



Drawing-No.: 6.544-5339.02-4

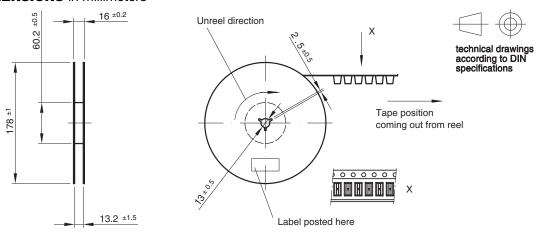
Issue: 3; 02.04.03

16760

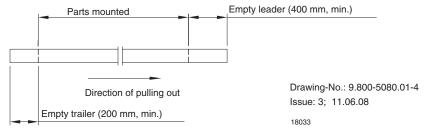




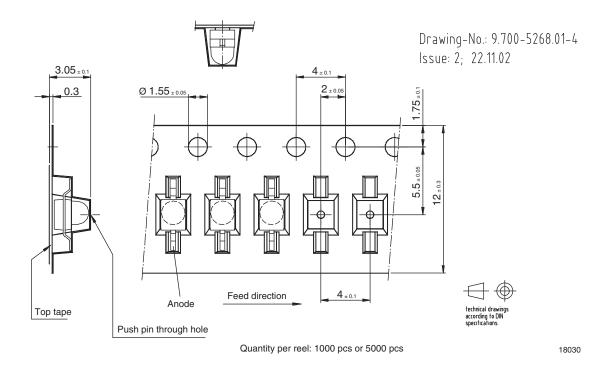
### **REEL DIMENSIONS** in millimeters



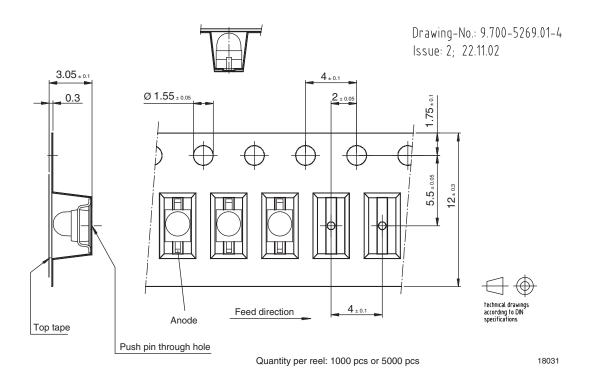
#### Leader and trailer tape:



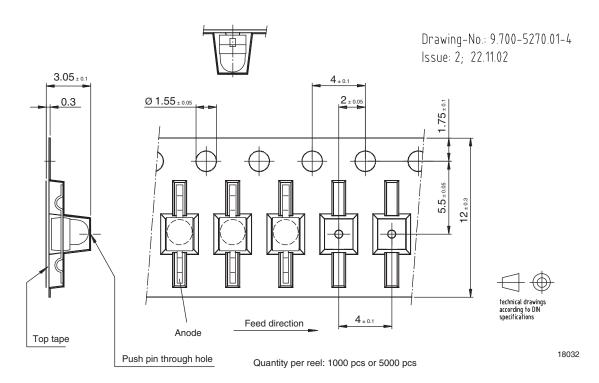
### TAPING DIMENSIONS in millimeters: TSML1000



### **TAPING DIMENSIONS** in millimeters: **TSML1020**



### TAPING DIMENSIONS in millimeters: TSML1030







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Document Number: 91000 www.vishay.com Revision: 11-Mar-11